

3SK317

Silicon N-Channel Dual Gate MOS FET UHF / VHF RF Amplifier

REJ03G1247-0200

(Previous: ADE-208-778)

Rev.2.00

Aug. 10, 2005

Features

• Low noise characteristics; (NF = 1.0 dB typ. at f = 200 MHz)

• High power gain characteristics; (PG = 27.6 dB typ. at f = 200 MHz)

Outline

RENESAS Package code: PTSP0004ZA-A

(Package name: CMPAK-4)



4. Drain

Note: Marking is "ZR-".

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	14	V	
Gate1 to source voltage	V _{G1S}	±8	V	
Gate2 to source voltage	V_{G2S}	±8	V	
Drain current	I _D	25	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

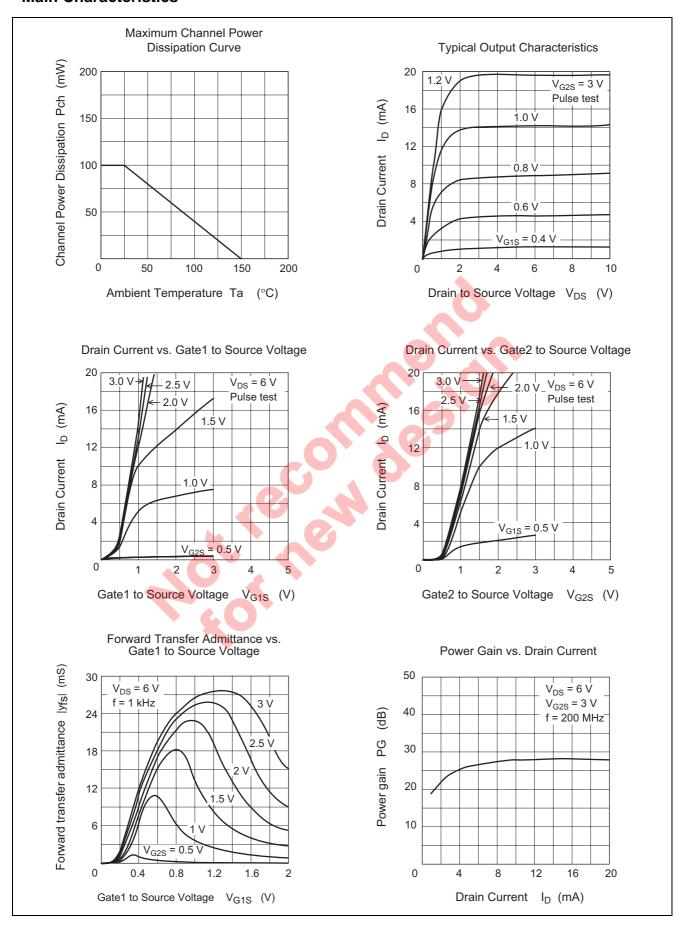
Electrical Characteristics

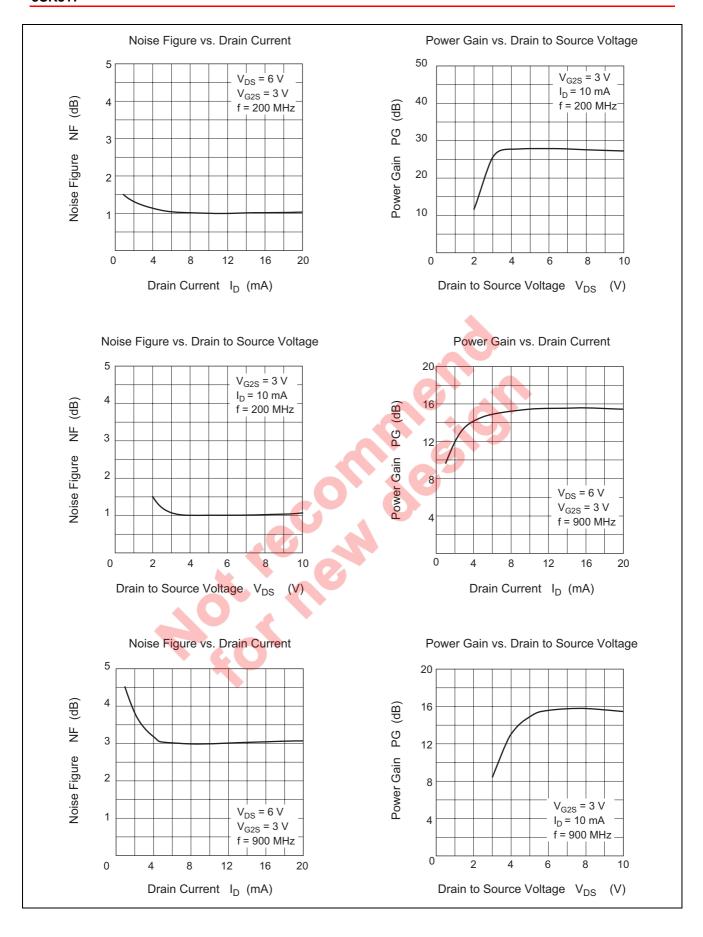
 $(Ta = 25^{\circ}C)$

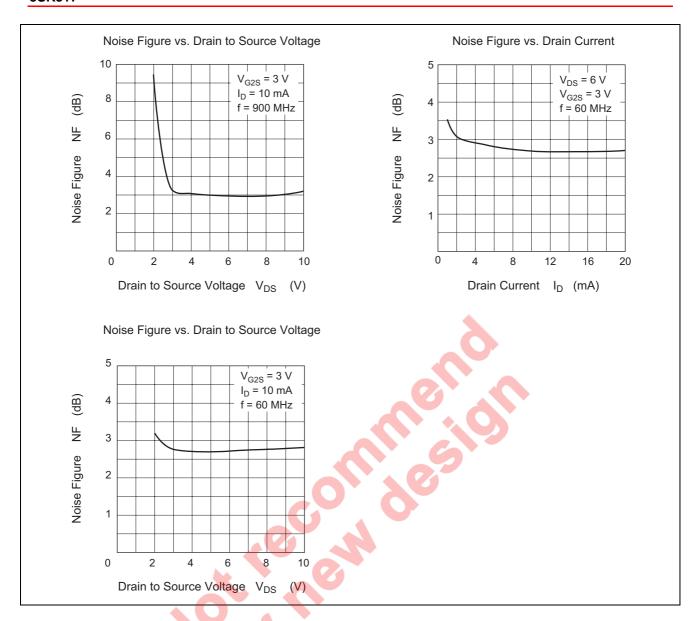
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	V _{(BR)DSS}	14	_	_	V	$I_D = 200~\mu A$, $V_{G1S} = V_{G2S} = -3~V$	
Gate1 to source breakdown voltage	$V_{(BR)G1SS}$	±8		_	V	$I_{G1} = \pm 10 \ \mu A, \ V_{G2S} = V_{DS} = 0$	
Gate2 to source breakdown voltage	$V_{(BR)G2SS}$	±8		_	>	$I_{G2} = \pm 10 \ \mu A, \ V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff current	I _{G1SS}	_		±100	nA	$V_{G1S} = \pm 6 \text{ V}, V_{G2S} = V_{DS} = 0$	
Gate2 to source cutoff current	I _{G2SS}	_		±100	nΑ	$V_{G2S} = \pm 6 \text{ V}, V_{G1S} = V_{DS} = 0$	
Gate1 to source cutoff voltage	$V_{G1S(off)}$	0	0.2	1	V	$V_{DS} = 10 \text{ V}, V_{G2S} = 3 \text{ V},$	
						I _D = 100 μA	
Gate2 to source cutoff voltage	$V_{G2S(off)}$	0	0.3	1	V	$V_{DS} = 10 \text{ V}, V_{G1S} = 3 \text{ V},$	
						I _D = 100 μA	
Drain current	I _{DS(op)}	4	8	14	mA	$V_{DS} = 6 \text{ V}, V_{G1S} = 0.75 \text{ V},$	
						$V_{G2S} = 3 V$	
Forward transfer admittance	y _{fs}	20	25		mS	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V}$	
						$I_D = 10 \text{ mA}, f = 1 \text{ kHz}$	
Input capacitance	Ciss	2.4	3.1	3.5	pF	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$	
Output capacitance	Coss	0.8	1.1	1.4	pF	$I_D = 10 \text{ mA}, f = 1 \text{ MHz}$	
Reverse transfer capacitance	Crss	+73	0.021	0.04	pF		
Power gain	PG	24	27.6	_	dB	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$	
Noise figure	NF		1.0	1.5	dB	I _D = 10 mA , f = 200 MHz	
Power gain	PG	12	15.6	_	dB	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{ V},$	
Noise figure	NF	_	3	4	dB	I _D = 10 mA, f = 900 MHz	
Noise figure	NF		2.7	3.5	dB	V _{DS} = 6 V, V _{G2S} = 3 V	
						I _D = 10 mA, f = 60 MHz	



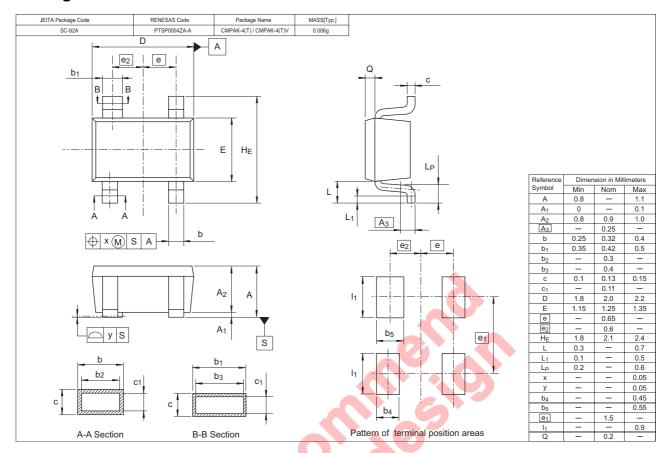
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity		Shipping Container
3SK317ZR-TL-E	3000		∮178 mm Reel, 8 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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